US-TC-720
Thermal Joint Compound

US-TC-720 is a high temperature thermal joint compound developed to fill gaps between heat sinks and substrates.

Fills microscopic voids between surfaces.

Retains its properties at elevated temperatures.

Works well in manual and automatic dispensing equipment.

Product Features
- Non hardening.
- High temperature rating of 600F.
- Non-organic thermal joint compound.
- Solvent free (meets California requirements)

Typical Applications
- Semiconductor assemblies
- High temperature heat sink compound
- Electric heating elements

Color: White

Service Temperature: -65°C to 315°C

Typical Properties

Uncured

Viscosity, cps: 100,000
Specific Gravity: 2.1
Consistency: light paste
Dielectric Strength: 225 volts/mil
Thermal conductivity: 0.735

Method of Application: Dispense product onto part and mate parts. Be sure not to squeeze all of the product out of assembly.

Solids: 98% solids, contains no solvents

Curing: Does not cure.

Limitations: None

Packaging: Available in 3ox tube, 6oz Semco, 8oz container, 10.3 oz cartridge. This product is also available in customer defined packaging sizes, upon request.

Handling and safety: For maximum shelf life, keep containers sealed when not in use. Keep out of the reach of children. Uncured sealant can irritate eyes and skin. Refer to MSDS.

Shelf-life: Sealed containers guaranteed for 5 years from the ship date when stored in a cool dry area below 70°F.